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### **Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### **Details**

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	69
Number of Gates	6000
Voltage - Supply	3V ~ 3.6V, 4.5V ~ 5.5V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	100-BQFP
Supplier Device Package	100-PQFP (20x14)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/a40mx04-1pq100i">https://www.e-xfl.com/product-detail/microchip-technology/a40mx04-1pq100i</a>

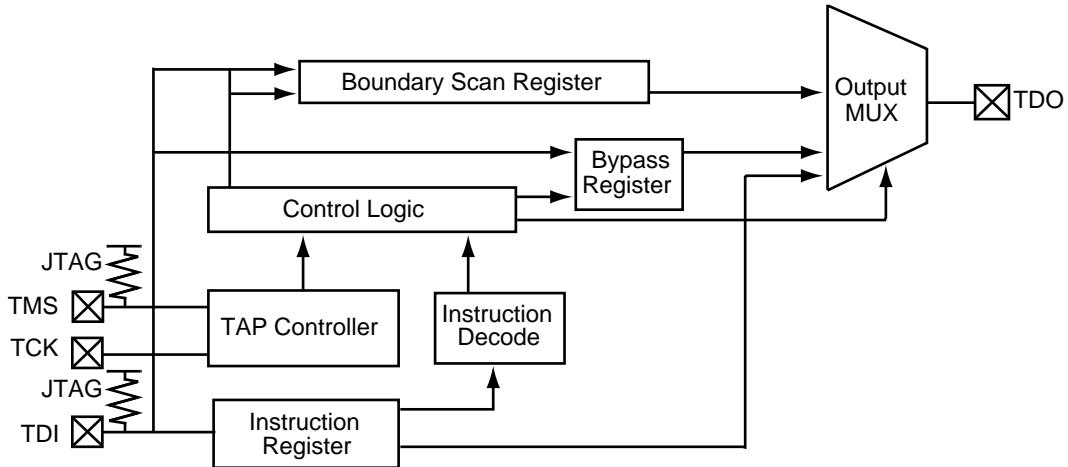
# Tables

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Table 1	Product profile .....	1
Table 2	Plastic Device Resources .....	4
Table 3	Ceramic Device Resources .....	4
Table 4	Temperature Grade Offerings .....	5
Table 5	Speed Grade Offerings .....	5
Table 6	Voltage Support of MX Devices .....	13
Table 7	Fixed Capacitance Values for MX FPGAs (pF) .....	16
Table 8	Device Configuration Options for Probe Capability .....	17
Table 9	Test Access Port Descriptions .....	18
Table 10	Supported BST Public Instructions .....	18
Table 11	Boundary Scan Pin Configuration and Functionality .....	19
Table 12	Absolute Maximum Ratings for 40MX Devices*	20
Table 13	Absolute Maximum Ratings for 42MX Devices*	20
Table 14	Recommended Operating Conditions .....	21
Table 15	5V TTL Electrical Specifications .....	21
Table 16	Absolute Maximum Ratings for 40MX Devices*	22
Table 17	Absolute Maximum Ratings for 42MX Devices*	22
Table 18	Recommended Operating Conditions .....	22
Table 19	3.3V LVTTL Electrical Specifications .....	23
Table 20	Absolute Maximum Ratings*	23
Table 21	Recommended Operating Conditions .....	24
Table 22	Mixed 5.0V/3.3V Electrical Specifications .....	25
Table 23	DC Specification (5.0 V PCI Signaling) .....	25
Table 24	AC Specifications (5.0V PCI Signaling)* .....	26
Table 25	DC Specification (3.3 V PCI Signaling) .....	27
Table 26	AC Specifications for (3.3 V PCI Signaling)* .....	27
Table 27	Package Thermal Characteristics .....	29
Table 28	42MX Temperature and Voltage Derating Factors (Normalized to $T_J = 25^\circ\text{C}$ , $\text{VCCA} = 5.0 \text{ V}$ ) .....	38
Table 29	40MX Temperature and Voltage Derating Factors(Normalized to $T_J = 25^\circ\text{C}$ , $\text{VCC} = 5.0 \text{ V}$ ) .....	38
Table 30	42MX Temperature and Voltage Derating Factors(Normalized to $T_J = 25^\circ\text{C}$ , $\text{VCCA} = 3.3 \text{ V}$ ) .....	39
Table 31	40MX Temperature and Voltage Derating Factors (Normalized to $T_J = 25^\circ\text{C}$ , $\text{VCC} = 3.3 \text{ V}$ ) .....	39
Table 32	Clock Specification for 33 MHz PCI .....	40
Table 33	Timing Parameters for 33 MHz PCI .....	40
Table 34	A40MX02 Timing Characteristics (Nominal 5.0 V Operation) .....	41
Table 35	A40MX02 Timing Characteristics (Nominal 3.3 V Operation) .....	43
Table 36	A40MX04 Timing Characteristics (Nominal 5.0 V Operation) (Worst-Case Commercial Conditions, $\text{VCC} = 4.75 \text{ V}$ , $T_J = 70^\circ\text{C}$ ) .....	46
Table 37	A40MX04 Timing Characteristics (Nominal 3.3 V Operation) (Worst-Case Commercial Conditions, $\text{VCC} = 3.0 \text{ V}$ , $T_J = 70^\circ\text{C}$ ) .....	49
Table 38	A42MX09 Timing Characteristics (Nominal 5.0 V Operation) (Worst-Case Commercial Conditions, $\text{VCCA} = 4.75 \text{ V}$ , $T_J = 70^\circ\text{C}$ ) .....	52
Table 39	A42MX09 Timing Characteristics (Nominal 3.3 V Operation) (Worst-Case Commercial Conditions, $\text{VCCA} = 3.0 \text{ V}$ , $T_J = 70^\circ\text{C}$ ) .....	56
Table 40	A42MX16 Timing Characteristics (Nominal 5.0 V Operation) (Worst-Case Commercial Conditions, $\text{VCCA} = 4.75 \text{ V}$ , $T_J = 70^\circ\text{C}$ ) .....	60
Table 41	A42MX16 Timing Characteristics (Nominal 3.3 V Operation) (Worst-Case Commercial Conditions, $\text{VCCA} = 3.0 \text{ V}$ , $T_J = 70^\circ\text{C}$ ) .....	64
Table 42	A42MX24 Timing Characteristics (Nominal 5.0 V Operation) (Worst-Case Commercial Conditions, $\text{VCCA} = 4.75 \text{ V}$ , $T_J = 70^\circ\text{C}$ ) .....	67
Table 43	A42MX24 Timing Characteristics (Nominal 3.3 V Operation) (Worst-Case Commercial Conditions, $\text{VCCA} = 3.0 \text{ V}$ , $T_J = 70^\circ\text{C}$ ) .....	71
Table 44	A42MX36 Timing Characteristics (Nominal 5.0 V Operation)(Worst-Case Commercial Conditions, $\text{VCCA} = 4.75 \text{ V}$ , $T_J = 70^\circ\text{C}$ ) .....	75
Table 45	A42MX36 Timing Characteristics (Nominal 3.3 V Operation) (Worst-Case Commercial Conditions, $\text{VCCA} = 3.0 \text{ V}$ , $T_J = 70^\circ\text{C}$ ) .....	75

Each I/O cell has three boundary-scan register cells, each with a serial-in, serial-out, parallel-in, and parallel-out pin. The serial pins are used to serially connect all the boundary-scan register cells in a device into a boundary-scan register chain, which starts at the TDI pin and ends at the TDO pin. The parallel ports are connected to the internal core logic tile and the input, output and control ports of an I/O buffer to capture and load data into the register to control or observe the logic state of each I/O.

**Figure 14 • 42MX IEEE 1149.1 Boundary Scan Circuitry**



**Table 9 • Test Access Port Descriptions**

Port	Description
TMS (Test Mode Select)	Serial input for the test logic control bits. Data is captured on the rising edge of the test logic clock (TCK).
TCK (Test Clock Input)	Dedicated test logic clock used serially to shift test instruction, test data, and control inputs on the rising edge of the clock, and serially to shift the output data on the falling edge of the clock. The maximum clock frequency for TCK is 20 MHz.
TDI (Test Data Input)	Serial input for instruction and test data. Data is captured on the rising edge of the test logic clock.
TDO (Test Data Output)	Serial output for test instruction and data from the test logic. TDO is set to an Inactive Drive state (high impedance) when data scanning is not in progress.

**Table 10 • Supported BST Public Instructions**

Instruction	IR Code (IR2.IR0)	Instruction Type	Description
EXTEST	000	Mandatory	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
SAMPLE/PRELOAD	001	Mandatory	Allows a snapshot of the signals at the device pins to be captured and examined during operation
HIGH Z	101	Optional	Tristates all I/Os to allow external signals to drive pins. See the IEEE Standard 1149.1 specification.
CLAMP	110	Optional	Allows state of signals driven from component pins to be determined from the Boundary-Scan Register. See the IEEE Standard 1149.1 specification for details.
BYPASS	111	Mandatory	Enables the bypass register between the TDI and TDO pins. The test data passes through the selected device to adjacent devices in the test chain.

Additionally, the back-annotation flow is compatible with all the major simulators and the simulation results can be cross-probed with Silicon Explorer II, Microsemi's integrated verification and logic analysis tool. Another tool included in the Libero software is the SmartGen macro builder, which easily creates popular and commonly used logic functions for implementation into your schematic or HDL design.

Microsemi's Libero software is compatible with the most popular FPGA design entry and verification tools from companies such as Mentor Graphics, Synopsys, and Cadence design systems.

See the Libero IDE web content at [www.microsemi.com/soc/products/software/libero/default.aspx](http://www.microsemi.com/soc/products/software/libero/default.aspx) for further information on licensing and current operating system support.

## 3.6 Related Documents

The following sections give the list of related documents which can be referred for this datasheet.

### 3.6.1 Application Notes

- AC278: *BSDL Files Format Description*
- AC225: *Programming Antifuse Devices*
- AC168: *Implementation of Security in Microsemi Antifuse FPGAs*

### 3.6.2 User Guides and Manuals

- *Antifuse Macro Library Guide*
- *Silicon Sculptor Programmers User Guide*

### 3.6.3 Miscellaneous

*Libero IDE Flow Diagram*

## 3.7 5.0 V Operating Conditions

The following tables show 5.0 V operating conditions.

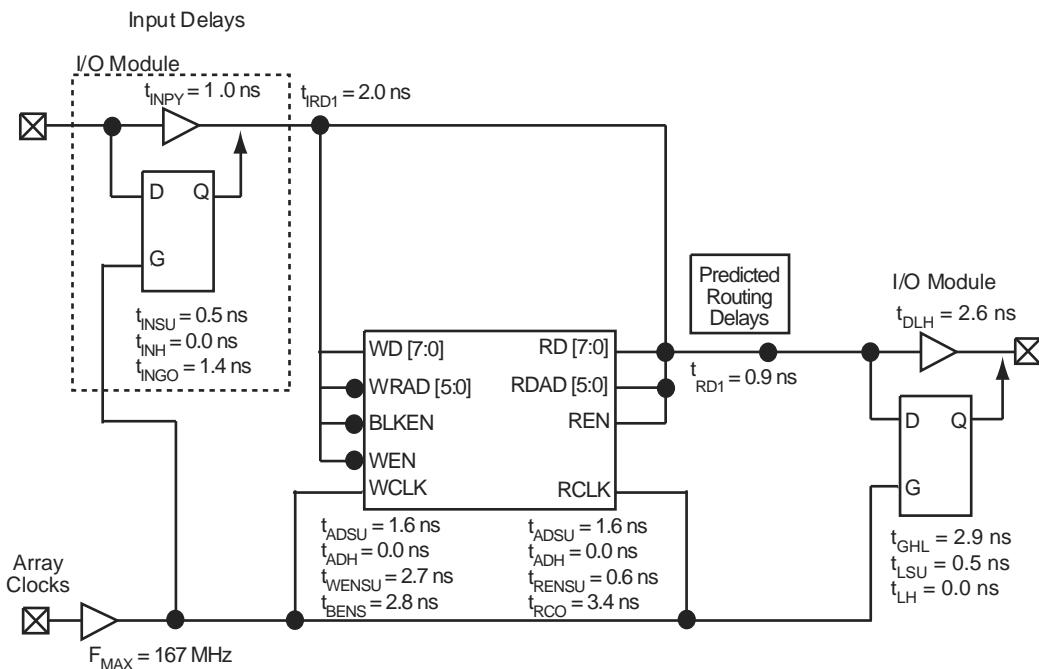
**Table 12 • Absolute Maximum Ratings for 40MX Devices\***

Symbol	Parameter	Limits	Units
VCC	DC Supply Voltage	-0.5 to +7.0	V
VI	Input Voltage	-0.5 to VCC+0.5	V
VO	Output Voltage	-0.5 to VCC+0.5	V
t <sub>STG</sub>	Storage Temperature	-65 to +150	°C

**Note:** \*Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum rated conditions for extended periods may affect device reliability. Devices should not be operated outside the recommended operating conditions.

**Table 13 • Absolute Maximum Ratings for 42MX Devices\***

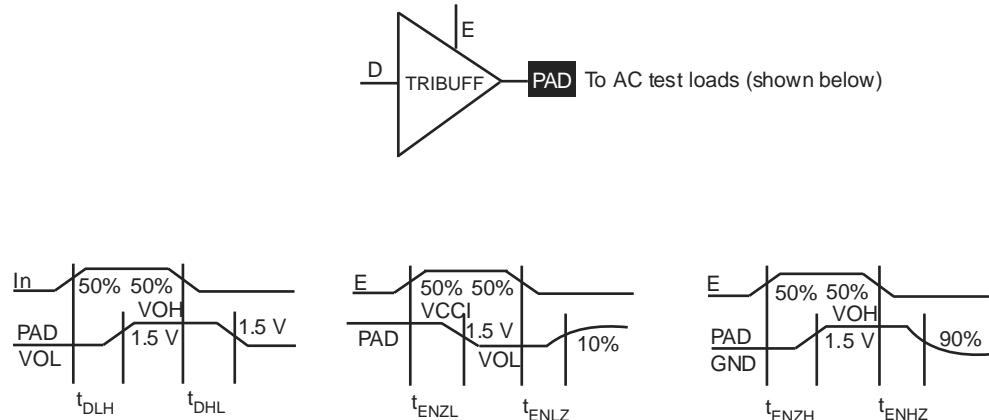
Symbol	Parameter	Limits	Units
VCCI	DC Supply Voltage for I/Os	-0.5 to +7.0	V
VCCA	DC Supply Voltage for Array	-0.5 to +7.0	V
VI	Input Voltage	-0.5 to VCCI+0.5	V
VO	Output Voltage	-0.5 to VCCI+0.5	V
t <sub>STG</sub>	Storage Temperature	-65 to +150	°C

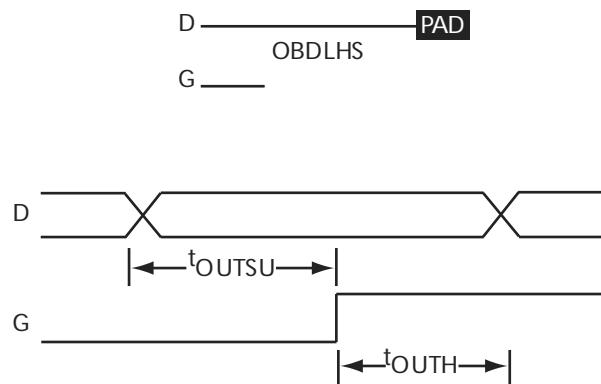
**Figure 20 • 42MX Timing Model (SRAM Functions)**

**Note:** Values are shown for A42MX36 –3 at 5.0 V worst-case commercial conditions.

### 3.10.1 Parameter Measurement

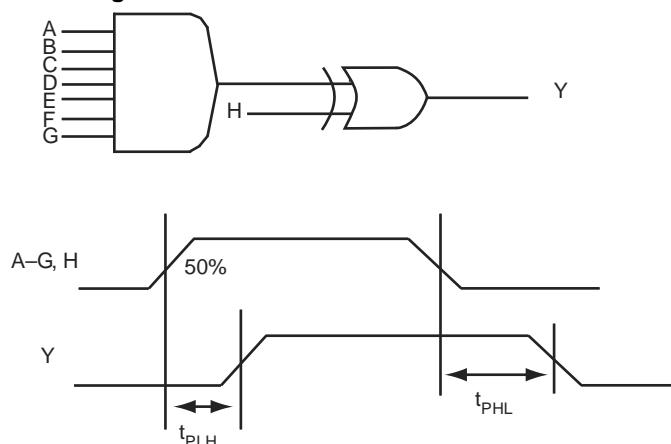
The following figures show parameter measurement details.

**Figure 21 • Output Buffer Delays**

**Figure 27 • Output Buffer Latches**

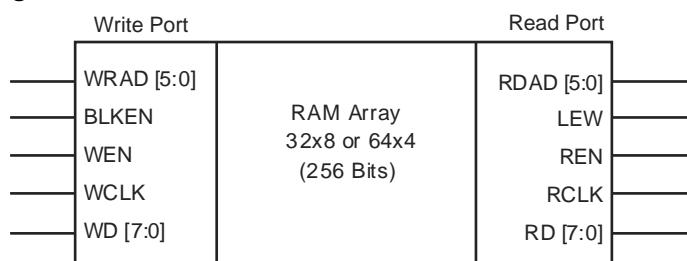
### 3.10.4 Decode Module Timing

The following figure shows decode module timing.

**Figure 28 • Decode Module Timing**

### 3.10.5 SRAM Timing Characteristics

The following figure shows SRAM timing characteristics.

**Figure 29 • SRAM Timing Characteristics**

### 3.10.6 Dual-Port SRAM Timing Waveforms

The following figures show dual-port SRAM timing waveforms.

**Table 35 • A40MX02 Timing Characteristics (Nominal 3.3 V Operation) (continued)**  
**(Worst-Case Commercial Conditions, VCC = 3.0 V, TJ = 70°C)**

<b>Parameter / Description</b>	<b>-3 Speed</b>		<b>-2 Speed</b>		<b>-1 Speed</b>		<b>Std Speed</b>		<b>-F Speed</b>		<b>Units</b>
	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	
t <sub>P</sub> Minimum Period	FO = 16	6.5		7.5		8.5		10.1		14.1	ns
	FO = 128	6.8		7.8		8.9		10.4		14.6	
f <sub>MAX</sub> Maximum Frequency	FO = 16		113		105		96		83		50 MHz
	FO = 128		109		101		92		80		48
<b>TTL Output Module Timing<sup>4</sup></b>											
t <sub>DLH</sub> Data-to-Pad HIGH			4.7		5.4		6.1		7.2		10.0 ns
t <sub>DHL</sub> Data-to-Pad LOW			5.6		6.4		7.3		8.6		12.0 ns
t <sub>ENZH</sub> Enable Pad Z to HIGH			5.2		6.0		6.8		8.1		11.3 ns
t <sub>ENZL</sub> Enable Pad Z to LOW			6.6		7.6		8.6		10.1		14.1 ns
t <sub>ENHZ</sub> Enable Pad HIGH to Z			11.1		12.8		14.5		17.1		23.9 ns
t <sub>ENLZ</sub> Enable Pad LOW to Z			8.2		9.5		10.7		12.6		17.7 ns
d <sub>TLH</sub> Delta LOW to HIGH			0.03		0.03		0.04		0.04		0.06 ns/pF
d <sub>THL</sub> Delta HIGH to LOW			0.04		0.04		0.05		0.06		0.08 ns/pF

**Table 37 • A40MX04 Timing Characteristics (Nominal 3.3 V Operation) (continued)(Worst-Case Commercial Conditions, VCC = 3.0 V, TJ = 70°C)**

<b>Parameter / Description</b>	<b>-3 Speed</b>		<b>-2 Speed</b>		<b>-1 Speed</b>		<b>Std Speed</b>		<b>-F Speed</b>		<b>Units</b>
	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	
t <sub>WCLKA</sub> Flip-Flop (Latch) Clock Active Pulse Width	4.6		5.3		5.6		7.0		9.8		ns
t <sub>WASYN</sub> Flip-Flop (Latch) Asynchronous Pulse Width	4.6		5.3		5.6		7.0		9.8		ns
t <sub>A</sub> Flip-Flop Clock Input Period	6.8		7.8		8.9		10.4		14.6		ns
f <sub>MAX</sub> Flip-Flop (Latch) Clock Frequency (FO = 128)		109		101		92		80		48	MHz
<b>Input Module Propagation Delays</b>											
t <sub>I NYH</sub> Pad-to-Y HIGH		1.0		1.1		1.3		1.5		2.1	ns
t <sub>I NYL</sub> Pad-to-Y LOW		0.9		1.0		1.1		1.3		1.9	ns

**Table 42 • A42MX24 Timing Characteristics (Nominal 5.0 V Operation) (continued)(Worst-Case Commercial Conditions, VCCA = 4.75 V, TJ = 70°C)**

<b>Parameter / Description</b>		<b>-3 Speed</b>		<b>-2 Speed</b>		<b>-1 Speed</b>		<b>Std Speed</b>		<b>-F Speed</b>		<b>Units</b>
		<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	
<b>Input Module Propagation Delays</b>												
t <sub>INPY</sub>	Input Data Pad-to-Y	1.0		1.1		1.3		1.5		2.1		ns
t <sub>INGO</sub>	Input Latch Gate-to-Output	1.3		1.4		1.6		1.9		2.6		ns
t <sub>INH</sub>	Input Latch Hold	0.0		0.0		0.0		0.0		0.0		ns
t <sub>INSU</sub>	Input Latch Set-Up	0.5		0.5		0.6		0.7		1.0		ns
t <sub>ILA</sub>	Latch Active Pulse Width	4.7		5.2		5.9		6.9		9.7		ns

**Table 45 • A42MX36 Timing Characteristics (Nominal 3.3 V Operation) (continued)(Worst-Case Commercial Conditions, VCCA = 3.0 V, TJ = 70°C)**

Parameter / Description	-3 Speed		-2 Speed		-1 Speed		Std Speed		-F Speed		Units
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>RD5</sub>	FO = 8 Routing Delay		4.6	5.2	5.8	6.9	6.9	9.6	9.6	ns	
t <sub>RDD</sub>	Decode-to-Output Routing Delay		0.5	0.5	0.6	0.7	0.7	1.0	1.0	ns	
<b>Logic Module Sequential Timing<sup>3, 4</sup></b>											
t <sub>CO</sub>	Flip-Flop Clock-to-Output		1.8	2.0	2.3	2.7	2.7	3.7	3.7	ns	
t <sub>GO</sub>	Latch Gate-to-Output		1.8	2.0	2.3	2.7	2.7	3.7	3.7	ns	
t <sub>SUD</sub>	Flip-Flop (Latch) Set-Up Time	0.4	0.5	0.6	0.7	0.7	0.9	0.9	ns		
t <sub>HD</sub>	Flip-Flop (Latch) Hold Time	0.0	0.0	0.0	0.0	0.0	0.0	0.0	ns		
t <sub>RO</sub>	Flip-Flop (Latch) Reset-to-Output	2.2	2.4	2.7	3.2	3.2	4.5	4.5	ns		
t <sub>SUENA</sub>	Flip-Flop (Latch) Enable Set-Up	1.0	1.1	1.2	1.4	1.4	2.0	2.0	ns		
t <sub>HENA</sub>	Flip-Flop (Latch) Enable Hold	0.0	0.0	0.0	0.0	0.0	0.0	0.0	ns		
t <sub>WCLKA</sub>	Flip-Flop (Latch) Clock Active Pulse Width	4.6	5.2	5.8	6.9	6.9	9.6	9.6	ns		
t <sub>WASYN</sub>	Flip-Flop (Latch) Asynchronous Pulse Width	6.1	6.8	7.7	9.0	9.0	12.6	12.6	ns		
<b>Synchronous SRAM Operations</b>											
t <sub>RC</sub>	Read Cycle Time		9.5	10.5	11.9	14.0	14.0	19.6	19.6	ns	
t <sub>WC</sub>	Write Cycle Time		9.5	10.5	11.9	14.0	14.0	19.6	19.6	ns	
t <sub>RCKHL</sub>	Clock HIGH/LOW Time		4.8	5.3	6.0	7.0	7.0	9.8	9.8	ns	
t <sub>RCO</sub>	Data Valid After Clock HIGH/LOW		4.8	5.3	6.0	7.0	7.0	9.8	9.8	ns	
t <sub>ADSU</sub>	Address/Data Set-Up Time		2.3	2.5	2.8	3.4	3.4	4.8	4.8	ns	

**Table 48 • PL68**

<b>PL68</b>		
<b>Pin Number</b>	<b>A40MX02 Function</b>	<b>A40MX04 Function</b>
24	I/O	I/O
25	VCC	VCC
26	I/O	I/O
27	I/O	I/O
28	I/O	I/O
29	I/O	I/O
30	I/O	I/O
31	I/O	I/O
32	GND	GND
33	I/O	I/O
34	I/O	I/O
35	I/O	I/O
36	I/O	I/O
37	I/O	I/O
38	VCC	VCC
39	I/O	I/O
40	I/O	I/O
41	I/O	I/O
42	I/O	I/O
43	I/O	I/O
44	I/O	I/O
45	I/O	I/O
46	I/O	I/O
47	I/O	I/O
48	I/O	I/O
49	GND	GND
50	I/O	I/O
51	I/O	I/O
52	CLK, I/O	CLK, I/O
53	I/O	I/O
54	MODE	MODE
55	VCC	VCC
56	SDI, I/O	SDI, I/O
57	DCLK, I/O	DCLK, I/O
58	PRA, I/O	PRA, I/O
59	PRB, I/O	PRB, I/O
60	I/O	I/O

**Table 52 • PQ160**

<b>PQ160</b>	<b>Pin Number</b>	<b>A42MX09 Function</b>	<b>A42MX16 Function</b>	<b>A42MX24 Function</b>
	95	I/O	I/O	I/O
	96	I/O	I/O	WD, I/O
	97	I/O	I/O	I/O
	98	VCCA	VCCA	VCCA
	99	GND	GND	GND
	100	NC	I/O	I/O
	101	I/O	I/O	I/O
	102	I/O	I/O	I/O
	103	NC	I/O	I/O
	104	I/O	I/O	I/O
	105	I/O	I/O	I/O
	106	I/O	I/O	WD, I/O
	107	I/O	I/O	WD, I/O
	108	I/O	I/O	I/O
	109	GND	GND	GND
	110	NC	I/O	I/O
	111	I/O	I/O	WD, I/O
	112	I/O	I/O	WD, I/O
	113	I/O	I/O	I/O
	114	NC	VCCI	VCCI
	115	I/O	I/O	WD, I/O
	116	NC	I/O	WD, I/O
	117	I/O	I/O	I/O
	118	I/O	I/O	TDI, I/O
	119	I/O	I/O	TMS, I/O
	120	GND	GND	GND
	121	I/O	I/O	I/O
	122	I/O	I/O	I/O
	123	I/O	I/O	I/O
	124	NC	I/O	I/O
	125	GND	GND	GND
	126	I/O	I/O	I/O
	127	I/O	I/O	I/O
	128	I/O	I/O	I/O
	129	NC	I/O	I/O
	130	GND	GND	GND
	131	I/O	I/O	I/O

**Table 52 • PQ160**

<b>PQ160</b>	<b>Pin Number</b>	<b>A42MX09 Function</b>	<b>A42MX16 Function</b>	<b>A42MX24 Function</b>
	132	I/O	I/O	I/O
	133	I/O	I/O	I/O
	134	I/O	I/O	I/O
	135	NC	VCCA	VCCA
	136	I/O	I/O	I/O
	137	I/O	I/O	I/O
	138	NC	VCCA	VCCA
	139	VCCI	VCCI	VCCI
	140	GND	GND	GND
	141	NC	I/O	I/O
	142	I/O	I/O	I/O
	143	I/O	I/O	I/O
	144	I/O	I/O	I/O
	145	GND	GND	GND
	146	NC	I/O	I/O
	147	I/O	I/O	I/O
	148	I/O	I/O	I/O
	149	I/O	I/O	I/O
	150	NC	VCCA	VCCA
	151	NC	I/O	I/O
	152	NC	I/O	I/O
	153	NC	I/O	I/O
	154	NC	I/O	I/O
	155	GND	GND	GND
	156	I/O	I/O	I/O
	157	I/O	I/O	I/O
	158	I/O	I/O	I/O
	159	MODE	MODE	MODE
	160	GND	GND	GND

**Table 54 • PQ240**

<b>PQ240</b>	
<b>Pin Number</b>	<b>A42MX36 Function</b>
126	WD, I/O
127	I/O
128	VCCI
129	I/O
130	I/O
131	I/O
132	WD, I/O
133	WD, I/O
134	I/O
135	QCLKB, I/O
136	I/O
137	I/O
138	I/O
139	I/O
140	I/O
141	I/O
142	WD, I/O
143	WD, I/O
144	I/O
145	I/O
146	I/O
147	I/O
148	I/O
149	I/O
150	VCCI
151	VCCA
152	GND
153	I/O
154	I/O
155	I/O
156	I/O
157	I/O
158	I/O
159	WD, I/O
160	WD, I/O
161	I/O
162	I/O

**Table 56 • VQ100**

<b>VQ100</b>		
<b>Pin Number</b>	<b>A42MX09 Function</b>	<b>A42MX16 Function</b>
57	I/O	I/O
58	I/O	I/O
59	I/O	I/O
60	I/O	I/O
61	I/O	I/O
62	LP	LP
63	VCCA	VCCA
64	VCCI	VCCI
65	VCCA	VCCA
66	I/O	I/O
67	I/O	I/O
68	I/O	I/O
69	I/O	I/O
70	GND	GND
71	I/O	I/O
72	I/O	I/O
73	I/O	I/O
74	I/O	I/O
75	I/O	I/O
76	I/O	I/O
77	SDI, I/O	SDI, I/O
78	I/O	I/O
79	I/O	I/O
80	I/O	I/O
81	I/O	I/O
82	GND	GND
83	I/O	I/O
84	I/O	I/O
85	PRA, I/O	PRA, I/O
86	I/O	I/O
87	CLKA, I/O	CLKA, I/O
88	VCCA	VCCA
89	I/O	I/O
90	CLKB, I/O	CLKB, I/O
91	I/O	I/O
92	PRB, I/O	PRB, I/O

**Table 58 • CQ208**

<b>CQ208</b>	
<b>Pin Number</b>	<b>A42MX36 Function</b>
1	GND
2	VCCA
3	MODE
4	I/O
5	I/O
6	I/O
7	I/O
8	I/O
9	I/O
10	I/O
11	I/O
12	I/O
13	I/O
14	I/O
15	I/O
16	I/O
17	VCCA
18	I/O
19	I/O
20	I/O
21	I/O
22	GND
23	I/O
24	I/O
25	I/O
26	I/O
27	GND
28	VCCI
29	VCCA
30	I/O
31	I/O
32	VCCA
33	I/O
34	I/O
35	I/O
36	I/O

**Table 59 • CQ256**

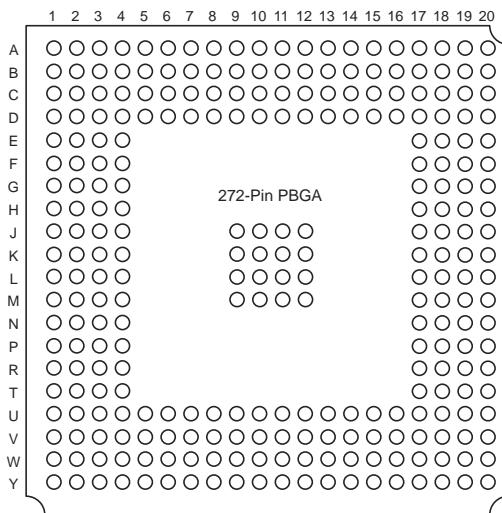
<b>CQ256</b>	
<b>Pin Number</b>	<b>A42MX36 Function</b>
133	I/O
134	I/O
135	I/O
136	I/O
137	I/O
138	I/O
139	GND
140	I/O
141	I/O
142	I/O
143	I/O
144	I/O
145	I/O
146	I/O
147	I/O
148	I/O
149	I/O
150	I/O
151	I/O
152	I/O
153	I/O
154	I/O
155	VCCA
156	I/O
157	I/O
158	VCCA
159	VCCI
160	GND
161	I/O
162	I/O
163	I/O
164	I/O
165	GND
166	I/O
167	I/O
168	I/O
169	I/O

**Table 59 • CQ256**

<b>CQ256</b>	
<b>Pin Number</b>	<b>A42MX36 Function</b>
207	I/O
208	I/O
209	QCLKC, I/O
210	I/O
211	WD, I/O
212	WD, I/O
213	I/O
214	I/O
215	WD, I/O
216	WD, I/O
217	I/O
218	PRB, I/O
219	I/O
220	CLKB, I/O
221	I/O
222	GND
223	GND
224	VCCA
225	VCCI
226	I/O
227	CLKA, I/O
228	I/O
229	PRA, I/O
230	I/O
231	I/O
232	WD, I/O
233	WD, I/O
234	I/O
235	I/O
236	I/O
237	I/O
238	I/O
239	I/O
240	QCLKD, I/O
241	I/O
242	WD, I/O
243	GND

**Table 59 • CQ256**

<b>CQ256</b>	
<b>Pin Number</b>	<b>A42MX36 Function</b>
244	WD, I/O
245	I/O
246	I/O
247	I/O
248	VCCI
249	I/O
250	WD, I/O
251	WD, I/O
252	I/O
253	SDI, I/O
254	I/O
255	GND
256	NC

**Figure 51 • BG272****Table 60 • BG272**

<b>BG272</b>	
<b>Pin Number</b>	<b>A42MX36 Function</b>
A1	GND
A2	GND
A3	I/O
A4	WD, I/O
A5	I/O

**Table 62 • CQ172**

99	I/O
100	I/O
101	I/O
102	I/O
103	GND
104	I/O
105	I/O
106	VKS
107	VPP
108	GND
109	VCCI
110	VSV
111	I/O
112	I/O
113	VCC
114	I/O
115	I/O
116	I/O
117	I/O
118	GND
119	I/O
120	I/O
121	I/O
122	I/O
123	GNDI
124	I/O
125	I/O
126	I/O
127	I/O
128	I/O
129	I/O
130	I/O
131	SDI
132	I/O
133	I/O
134	I/O
135	I/O
136	VCCI
137	I/O

**Table 62 • CQ172**

138	I/O
139	I/O
140	I/O
141	GND
142	I/O
143	I/O
144	I/O
145	I/O
146	I/O
147	I/O
148	PROBA
149	I/O
150	CLKA
151	VCC
152	GND
153	I/O
154	CLKB
155	I/O
156	PROBB
157	I/O
158	I/O
159	I/O
160	I/O
161	GND
162	I/O
163	I/O
164	I/O
165	I/O
166	VCCI
167	I/O
168	I/O
169	I/O
170	I/O
171	DCLK